



### POWER DISSIPATION (PLP(DFN)1616-6B)

This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board.

This specification is based on the measurement at the condition below:

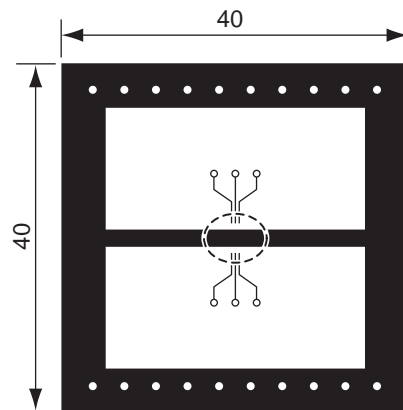
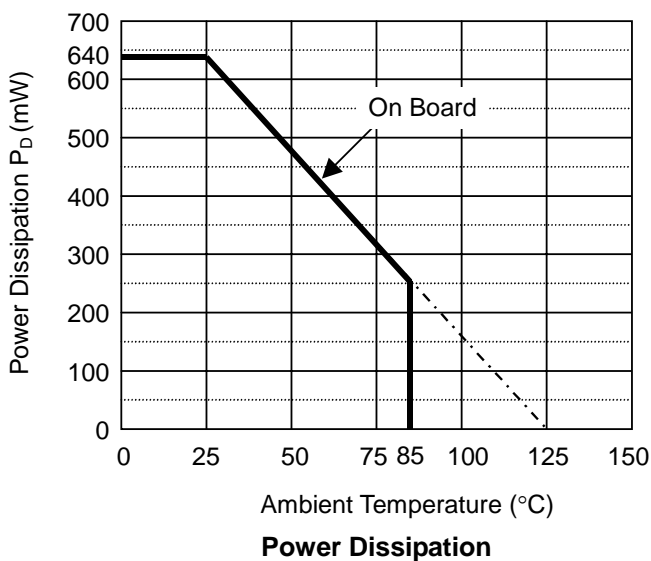
(DFN(PLP)1616-6B is a reference value calculated from the DFN(PLP)1820-6 package.)

Measurement Conditions

Standard Land Pattern	
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-holes	φ0.54mm × 26pcs

Measurement Results (T<sub>opt</sub>=25°C, T<sub>jmax</sub>=125°C)

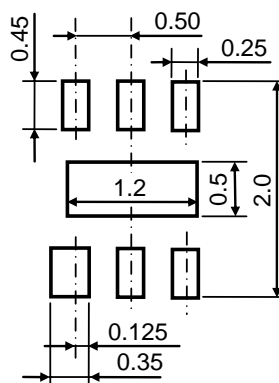
Standard Land Pattern	
Power Dissipation	640mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/0.64\text{W}=156^{\circ}\text{C/W}$
Thermal Resistance	$\theta_{jc}=23^{\circ}\text{C/W}$



Measurement Board Pattern

○ IC Mount Area (Unit: mm)

### RECOMMENDED LAND PATTERN



(Unit: mm)